

Single Inverter

The NL17SG04 MiniGate™ is an advanced high-speed CMOS Inverter in ultra-small footprint.

The NL17SG04 input structures provides protection when voltages up to 4.6 V are applied.

Features

- Wide Operating V_{CC} Range: 0.9 V to 3.6 V
- High Speed: $t_{PD} = 2.3$ ns (Typ) at $V_{CC} = 3.0$ V, $C_L = 15$ pF
- Low Power Dissipation: $I_{CC} = 0.5$ μ A (Max) at $T_A = 25^\circ\text{C}$
- 4.6 V Overvoltage Tolerant (OVT) Input Pins
- Ultra-Small Packages
- These are Pb-Free and Halide-Free Devices

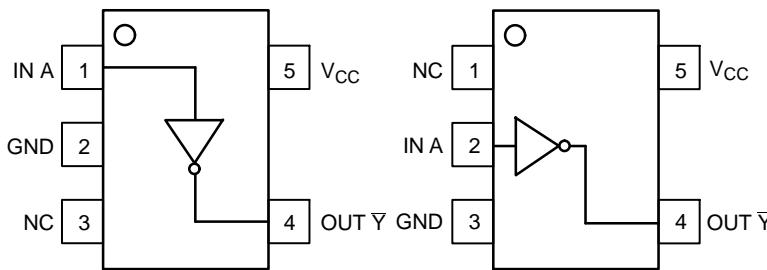


Figure 1. SOT-953
(Top Thru View)

Figure 2. SC-88A
(Top View)

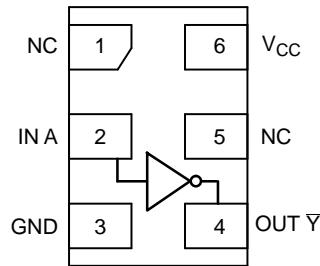


Figure 3. UDFN
(Top View)

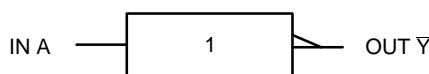


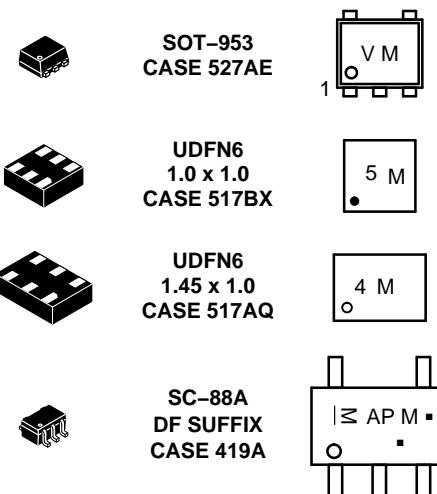
Figure 4. Logic Symbol



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MARKING DIAGRAMS



M = Date Code*

▪ = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.

PIN ASSIGNMENT

	SOT-953	SC-88A	UDFN6
1	IN A	NC	NC
2	GND	IN A	IN A
3	NC	GND	GND
4	OUT Y	OUT Y	OUT Y
5	V _{CC}	V _{CC}	NC
6			V _{CC}

FUNCTION TABLE

A Input	Y Output
L	H
H	L

ORDERING INFORMATION

See detailed ordering and shipping information on page 5 of this data sheet.

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage	−0.5 to +5.5	V
V_{IN}	DC Input Voltage	−0.5 to +4.6	V
V_{OUT}	DC Output Voltage Output at High or Low State Power-Down Mode ($V_{CC} = 0$ V)	−0.5 to V_{CC} +0.5 −0.5 to +4.6	V
I_{IK}	DC Input Diode Current $V_{IN} < GND$	−20	mA
I_{OK}	DC Output Diode Current $V_{OUT} < GND$	−20	mA
I_{OUT}	DC Output Source/Sink Current	±20	mA
I_{CC}	DC Supply Current per Supply Pin	±20	mA
I_{GND}	DC Ground Current per Ground Pin	±20	mA
T_{STG}	Storage Temperature Range	−65 to +150	°C
T_L	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C
T_J	Junction Temperature Under Bias	+150	°C
MSL	Moisture Sensitivity	Level 1	
F_R	Flammability Rating Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
V_{ESD}	ESD Withstand Voltage Human Body Model (Note 2) Machine Model (Note 3)	>2000 >100	V
$I_{LATCHUP}$	Latchup Performance Above V_{CC} and Below GND at 125°C (Note 4)	±100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.
2. Tested to EIA/JESD22-A114-A.
3. Tested to EIA/JESD22-A115-A.
4. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Characteristics	Min	Max	Unit
V_{CC}	Positive DC Supply Voltage	0.9	3.6	V
V_{IN}	Digital Input Voltage	0.0	3.6	V
V_{OUT}	Output Voltage Output at High or Low State Power-Down Mode ($V_{CC} = 0$ V)	0.0 0.0	V_{CC} 3.6	V
T_A	Operating Temperature Range	−55	+125	°C
$\Delta t / \Delta V$	Input Transition Rise or Fail Rate $V_{CC} = 3.3$ V ± 0.3 V	0	10	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Conditions	V _{CC} (V)	T _A = 25°C		T _A = -55°C to +125°C		Unit
				Min	Max	Min	Max	
V _{IH}	High-Level Input Voltage		0.9	V _{CC}		V _{CC}		V
			1.1 to 1.3	0.7xV _{CC}		0.7xV _{CC}		
			1.4 to 1.6	0.65xV _{CC}		0.65xV _{CC}		
			1.65 to 1.95	0.65xV _{CC}		0.65xV _{CC}		
			2.3 to 2.7	1.7		1.7		
			3.0 to 3.6	2.0		2.0		
V _{IL}	Low-Level Input Voltage		0.9		GND		GND	V
			1.1 to 1.3		0.3xV _{CC}		0.3xV _{CC}	
			1.4 to 1.6		0.35xV _{CC}		0.35xV _{CC}	
			1.65 to 1.95		0.35xV _{CC}		0.35xV _{CC}	
			2.3 to 2.7		0.7		0.7	
			3.0 to 3.6		0.8		0.8	
V _{OH}	High-Level Output Voltage	V _{IN} = V _{IH} or V _{IL}	I _{OH} = -20 μA	0.9	0.75		0.75	V
			I _{OH} = -0.3 mA	1.1 to 1.3	0.75xV _{CC}		0.75xV _{CC}	
			I _{OH} = -1.7 mA	1.4 to 1.6	0.75xV _{CC}		0.75xV _{CC}	
			I _{OH} = -3.0 mA	1.65 to 1.95	V _{CC} -0.45		V _{CC} -0.45	
			I _{OH} = -4.0 mA	2.3 to 2.7	2.0		2.0	
			I _{OH} = -8.0 mA	3.0 to 3.6	2.48		2.48	
V _{OL}	Low-Level Output Voltage	V _{IN} = V _{IH} or V _{IL}	I _{OL} = 20 μA	0.9		0.1		V
			I _{OL} = 0.3 mA	1.1 to 1.3		0.25xV _{CC}		
			I _{OL} = 1.7 mA	1.4 to 1.6		0.25xV _{CC}		
			I _{OL} = 3.0 mA	1.65 to 1.95		0.45		
			I _{OL} = 4.0 mA	2.3 to 2.7		0.4		
			I _{OL} = 8.0 mA	3.0 to 3.6		0.4		
I _{IN}	Input Leakage Current	0 ≤ V _{IN} ≤ 3.6 V	0 to 3.6		±0.1		±1.0	μA
I _{CC}	Quiescent Supply Current	V _{IN} = V _{CC} or GND	3.6		0.5		10.0	μA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

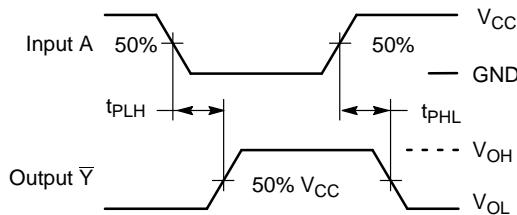
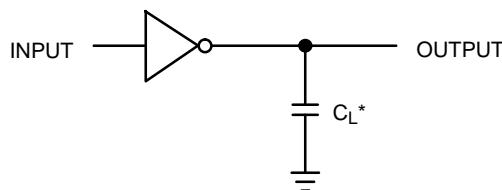
NL17SG04

AC ELECTRICAL CHARACTERISTICS Input $t_r = t_f = 3.0$ ns

Symbol	Parameter	Test Condition	V _{CC} (V)	T _A = 25°C			T _A = -55°C to +125°C		Unit
				Min	Typ	Max	Min	Max	
t _{PLH} , t _{PHL}	Propagation Delay, A to Y	C _L = 10 pF, R _L = 1 MΩ	0.9	-	10.0	13.3	-	17.0	ns
			1.1 to 1.3	-	8.7	11.2	-	14.0	
			1.4 to 1.6	-	4.9	8.5	-	10.0	
			1.65 to 1.95	-	3.8	6.2	-	6.7	
			2.3 to 2.7	-	2.6	3.9	-	4.4	
			3.0 to 3.6	-	2.1	3.1	-	3.7	
		C _L = 15 pF, R _L = 1 MΩ	0.9	-	11.55	13.7	-	19.7	ns
			1.1 to 1.3	-	7.2	10.8	-	15.6	
			1.4 to 1.6	-	5.4	9.3	-	11.2	
			1.65 to 1.95	-	4.2	6.9	-	7.1	
			2.3 to 2.7	-	2.8	4.4	-	5.0	
			3.0 to 3.6	-	2.3	3.4	-	3.9	
C _{IN}	Input Capacitance	C _L = 30 pF, R _L = 1 MΩ	0.9	-	16.85	18.9	-	22.3	ns
			1.1 to 1.3	-	10.2	13.4	-	17.5	
			1.4 to 1.6	-	7.4	13.1	-	15.9	
			1.65 to 1.95	-	5.6	9.2	-	9.6	
			2.3 to 2.7	-	3.7	5.7	-	6.1	
			3.0 to 3.6	-	2.9	4.4	-	4.8	
C _{IN}	Input Capacitance		0 to 3.6		3	-	-	-	pF
C _{PD}	Power Dissipation Capacitance (Note 5)	f = 10 MHz	0.9 to 3.6	-	4	-	-	-	pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

5. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}. C_{PD} is used to determine the no-load dynamic power consumption; P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.

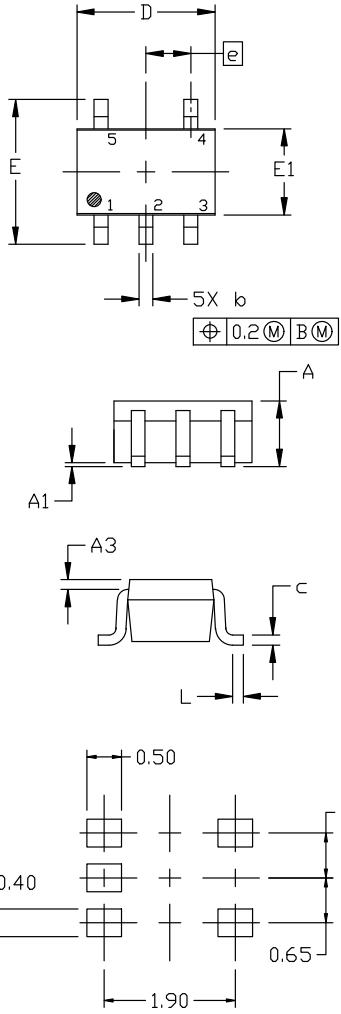
**Figure 5. Switching Waveforms**

*Includes all probe and jig capacitance.
A 1-MHz square input wave is recommended
for propagation delay tests.

Figure 6. Test Circuit**ORDERING INFORMATION**

Device	Package	Shipping [†]
NL17SG04P5T5G	SOT-953 (Pb-Free)	8000 / Tape & Reel
NL17SG04DFT2G	SC-88A (Pb-Free)	3000 / Tape & Reel
NL17SG04AMUTCG	UDFN6 1.45x1 mm (Pb-Free)	3000 / Tape & Reel
NL17SG04CMUTCG	UDFN6 1x1 mm (Pb-Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



**RECOMMENDED
MOUNTING FOOTPRINT**

- * For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

STYLE 1:
PIN 1. BASE
2. Emitter
3. BASE
4. COLLECTOR
5. COLLECTOR

STYLE 6:
PIN 1. Emitter 2
2. BASE 2
3. Emitter 1
4. COLLECTOR
5. COLLECTOR 2/BASE 1

STYLE 2:
PIN 1. ANODE
2. Emitter
3. BASE
4. COLLECTOR
5. CATHODE

STYLE 7:
PIN 1. BASE
2. Emitter
3. BASE
4. COLLECTOR
5. COLLECTOR

STYLE 3:
PIN 1. ANODE 1
2. N/C
3. ANODE 2
4. CATHODE 2
5. CATHODE 1

STYLE 8:
PIN 1. CATHODE
2. COLLECTOR
3. N/C
4. BASE
5. Emitter

STYLE 4:
PIN 1. SOURCE 1
2. DRAIN 1/2
3. SOURCE 1
4. GATE 1
5. GATE 2

STYLE 9:
PIN 1. ANODE
2. CATHODE
3. ANODE
4. ANODE
5. ANODE

STYLE 5:
PIN 1. CATHODE
2. COMMON ANODE
3. CATHODE 2
4. CATHODE 3
5. CATHODE 4

Note: Please refer to datasheet for style callout. If style type is not called out in the datasheet refer to the device datasheet pinout or pin assignment.

SC-88A (SC-70-5/SOT-353)
CASE 419A-02
ISSUE M

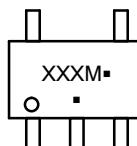
DATE 11 APR 2023

NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS
3. 419A-01 OBSOLETE. NEW STANDARD 419A-02
4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.1016MM PER SIDE.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.80	0.95	1.10
A1	---	---	0.10
A3 0.20 REF			
b	0.10	0.20	0.30
c	0.10	---	0.25
D	1.80	2.00	2.20
E	2.00	2.10	2.20
E1	1.15	1.25	1.35
e	0.65 BSC		
L	0.10	0.15	0.30

**GENERIC MARKING
DIAGRAM***



*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

XXX = Specific Device Code

M = Date Code
■ = Pb-Free Package

(Note: Microdot may be in either location)

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MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

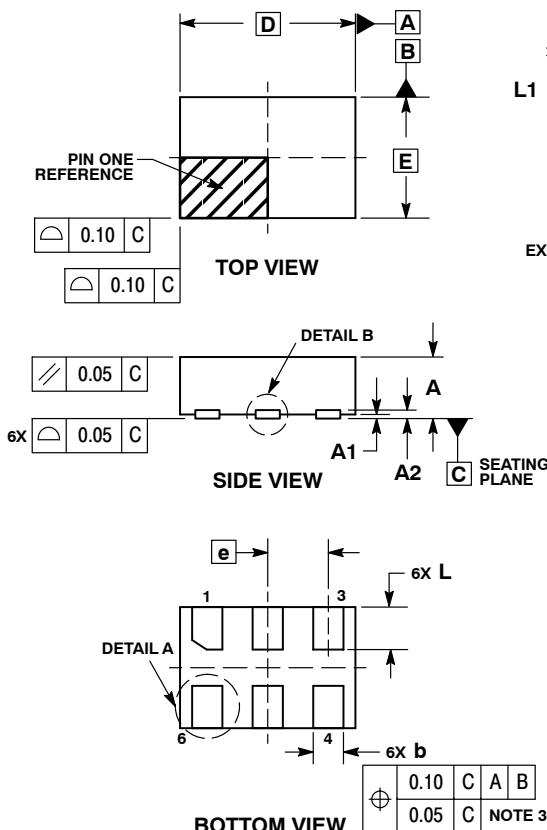
onsemiTM



SCALE 4:1

UDFN6, 1.45x1.0, 0.5P
CASE 517AQ
ISSUE O

DATE 15 MAY 2008

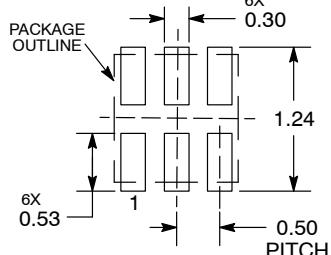


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION *b* APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.

DIM	MILLIMETERS	
	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A2	0.07 REF	
b	0.20	0.30
D	1.45 BSC	
E	1.00 BSC	
e	0.50 BSC	
L	0.30	0.40
L1	---	0.15

MOUNTING FOOTPRINT



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

**GENERIC
MARKING DIAGRAM***



X = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present.

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MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

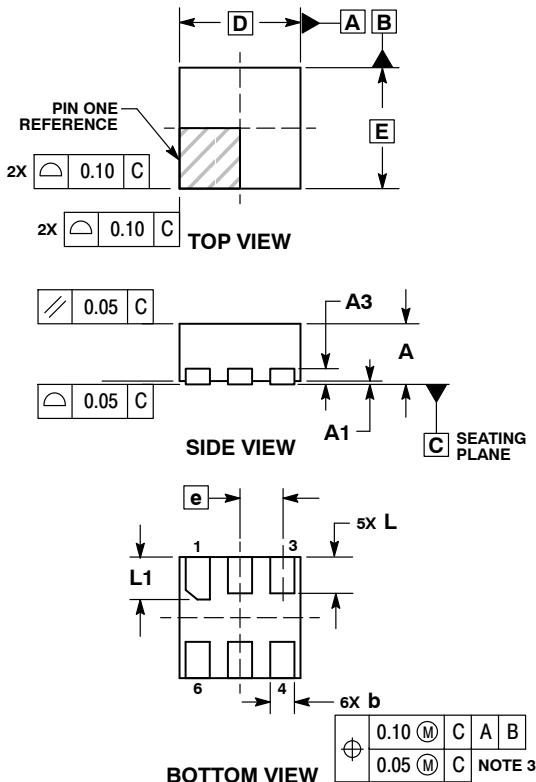
onsemiTM



SCALE 4:1

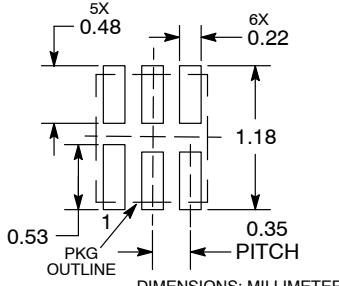
UDFN6, 1x1, 0.35P
CASE 517BX
ISSUE O

DATE 18 MAY 2011



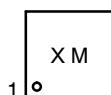
DIM.	MILLIMETERS	
	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.13 REF	
b	0.12	0.22
D	1.00 BSC	
E	1.00 BSC	
e	0.35 BSC	
L	0.25	0.35
L1	0.30	0.40

**RECOMMENDED
SOLDERING FOOTPRINT***



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**GENERIC
MARKING DIAGRAM***



X = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

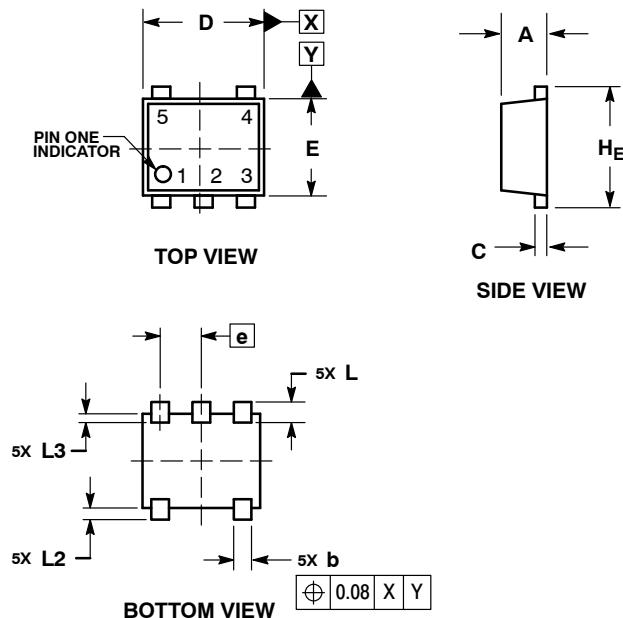
onsemiTM



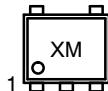
SCALE 4:1

SOT-953
CASE 527AE
ISSUE E

DATE 02 AUG 2011



**GENERIC
MARKING DIAGRAM***



X = Specific Device Code
M = Month Code

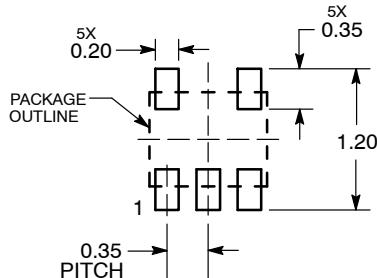
*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.34	0.37	0.40
b	0.10	0.15	0.20
C	0.07	0.12	0.17
D	0.95	1.00	1.05
E	0.75	0.80	0.85
e	0.35	0.35 BSC	
H _E	0.95	1.00	1.05
L	0.175	REF	
L ₂	0.05	0.10	0.15
L ₃	---	---	0.15

**RECOMMENDED
SOLDERING FOOTPRINT***



DIMENSIONS: MILLIMETERS

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DESCRIPTION:	SOT-953	PAGE 1 OF 1

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